

## Epoxy Technology EPO-TEK® H37-MPT Epoxy

Category : Polymer , Thermoset , Epoxy

### Material Notes:

**Material Description:** A single component, silver-filled and electrically conductive adhesive designed for semiconductor die attach and bonding SMDs for hybrid microelectronic packaging. It is certified and lot accepted to the requirements of MIL-STD 883 /Test Method 5011. It can be used for opto-packaging including LEDs, laser and photo-diodes, and fiber optic circuit assembly. Information Provided by Epoxy Technology

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Epoxy-Technology-EPO-TEK-H37-MPT-Epoxy.php](http://www.lookpolymers.com/polymer_Epoxy-Technology-EPO-TEK-H37-MPT-Epoxy.php)

Physical Properties	Metric	English	Comments
Specific Gravity	3.37 g/cc	3.37 g/cc	
Particle Size	<= 20 µm	<= 20 µm	
Viscosity	80000 - 110000 cP @Temperature 23.0 °C	80000 - 110000 cP @Temperature 73.4 °F	2.5 rpm

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	76	76	
Tensile Modulus	3.72 GPa	539 ksi	Storage
Shear Strength	11.69 MPa	1696 psi	Lap
	>= 23.4 MPa	>= 3400 psi	Die

Thermal Properties	Metric	English	Comments
CTE, linear	44.0 µm/m-°C	24.4 µin/in-°F	Below Tg
	108 µm/m-°C	60.0 µin/in-°F	Above Tg
Thermal Conductivity	2.82 W/m-K	19.6 BTU-in/hr-ft <sup>2</sup> -°F	
Maximum Service Temperature, Air	200 °C	392 °F	Continuous
	300 °C	572 °F	Intermittent
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	Intermittent
	-55.0 °C	-67.0 °F	Continuous
Glass Transition Temp, Tg	>= 90.0 °C	>= 194 °F	Dynamic Cure 20–200°C /ISO 25 Min; Ramp -10–200°C @ 20°C/Min
Decomposition Temperature	350 °C	662 °F	Degradation Temperature

Thermal Properties	Metric	English	Comments
Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.00050 ohm-cm	<= 0.00050 ohm-cm	

Chemical Properties	Metric	English	Comments
Ionic Impurities - Na (Sodium)	<= 50 ppm	<= 50 ppm	
Ionic Impurities - K (Potassium)	<= 50 ppm	<= 50 ppm	
Ionic Impurities - Cl (Chloride)	<= 200 ppm	<= 200 ppm	

Processing Properties	Metric	English	Comments
Cure Time	60.0 min @Temperature 150 °C	1.00 hour @Temperature 302 °F	Minimum
Pot Life	40320 min	40320 min	
Shelf Life	12.0 Month @Temperature -40.0 °C	12.0 Month @Temperature -40.0 °F	

Descriptive Properties	Value	Comments
Color	Silver	
Consistency	Smooth thixotropic paste	
Ionic Impurities NH4	53 ppm	
Number of Components	Single	
Weight Loss	0.01%	200°C

## Contact Songhan Plastic Technology Co.,Ltd.

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